	IGNER OLECULES	NC.	PRODUCT SELECTOR GUIDE							
PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS		
ANTI-B	ANTI-BLEEDS									
A6150	A-6150	1151519-17-3 (Y)	A proprietary <b>non-</b> <b>halogenated</b> additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control copper surfaces) with minimal or no affect on the adhesion properties of the formulation.	Unavailable	<ul> <li>Excellent bleed control</li> <li>Co-curable in free-radical polymerization</li> <li>Minimal adhesion degradation</li> <li>Non-halogenated- a 'green' alternative to conventional anti-bleed and mold release materials</li> </ul>	Yellow Liquid	100	<ul> <li>For use as an additive to reduce resin bleed out specifically on metal surfaces</li> </ul>		
A6225	A-6225	224704-15-1 (N)	Antibleed Additive – Silicone Mercapto Propionate (SMP). A proprietary <b>non-</b> <b>halogenated</b> additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control gold surfaces) with minimal or no affect on the adhesion properties of the formulation.	Unavailable	<ul> <li>Excellent bleed control</li> <li>Co-curable in most systems</li> <li>Minimal adhesion degradation</li> <li>Non-halogenated – a 'green' alternative to conventional anti-bleed and mold release materials</li> </ul>	Colorless Liquid	50	<ul> <li>For use as an additive to reduce resin bleed out specifically on metal surfaces</li> </ul>		
A6265	A-6265	2225898-70-2 (N)	A proprietary <b>non-</b> <b>halogenated</b> additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control copper surfaces) with minimal or no affect on the adhesion properties of the formulation.	Unavailable	<ul> <li>Excellent bleed control</li> <li>Co-curable in free-radical polymerization</li> <li>Minimal adhesion degradation</li> <li>Non-halogenated- a 'green' alternative to conventional anti-bleed and mold release materials</li> </ul>	Yellow Liquid	100	<ul> <li>For use as an additive to reduce resin bleed out specifically on metal surfaces</li> </ul>		
A6280	A-6280	2999663-83-9 (N)	A proprietary <b>non-</b> <b>halogenated</b> additive designed to reduce resin bleed out on a variety of surfaces (especially difficult to control gold surfaces) with minimal or no affect on the adhesion properties of the formulation.	Unavailable	<ul> <li>Excellent bleed control</li> <li>Co-curable in free-radical polymerization</li> <li>Minimal adhesion degradation</li> <li>Non-halogenated – a 'green' alternative to conventional anti-bleed and mold release materials</li> </ul>	Yellow Liquid	63	<ul> <li>For use as an additive to reduce resin bleed out specifically on metal surfaces</li> </ul>		

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PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS		
FUNCTIONAL ADDITIVES										
A6165	A-6165	1151654-51-1 (Y)	Soluble additive that on addition to a conductive adhesive formulation can significantly decrease the volume resistivity of the cured material	Unavailable	<ul> <li>Improves electrical conductivity in metal filed conductive paste formulations</li> <li>Soluble in most resin systems</li> <li>May improve thermal conductivity in some formulations</li> </ul>	Dark Brown / Black	Very viscous	<ul> <li>Increases electrical conductivity of resin system</li> </ul>		
A6220	A-284	93158-39-5 (Y)	Dibutyl-1,4 Cyclohexanedicarboxylate	H <sub>3</sub> C 0 0 CH <sub>3</sub>	<ul><li>Plasticizer</li><li>Non-phthalate</li><li>Very low viscosity</li></ul>	Colorless Liquid	30	• For use as a plasticizer in applications where human contact is expected		
R1217-M	A-478-M	111308-10-2 (N)	Pyromellitic Dianhydride Dimethacrylate – Mixture of Isomers	$\begin{array}{c} & & \\ & & \\ & & \\ H_{3}C \\ & \\ H_{2}C \\ & \\ H_{2}C$	<ul> <li>Versatile adhesion promoter</li> </ul>	Fine White Powder	Solid	Adhesion promoter		
R1231	A-304	70293-55-9 (N)	4-Metacryloxyethyl Trimellitic Anhydride	H <sub>3</sub> C H <sub>2</sub> O O O O O O O O O O	<ul> <li>Adhesion Promoter</li> <li>Versatile adhesion promoter</li> </ul>	White Powder / Crystals	Solid	Adhesion promoter		
R1251	A-675- 100%	148019-46-9 (Y)	PMGDM	$H_{3}C + CH_{2} + CH_{2} + CH_{3} + C$	<ul> <li>Versatile adhesion promoter</li> </ul>	Light Yellow	Very viscous	Adhesion promoter		

	IGNER OLECULES I	NC.	PRODUCT SELECTOR GUIDE							
PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS		
IMIDE-EXTENDED BISMALEIMIDES										
R1090	BMI-3000 Gel	921213-77-6 (Y)	Bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides.	Where n = 1 to 10	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>Superior thermal stability</li> </ul>	Red-Amber Gel	Solid	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> <li>Adhesion to metal</li> </ul>		
R1155	BMI-689	Original: 682800-79-9 Current: 1911605-95-2 (Y)	A unique very low viscosity BMI resin	H <sub>3</sub> C Contains unsaturation	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>Superior thermal stability</li> </ul>	Yellow to Amber Liquid	1,500 ± 500	Base resin or additive in thermoset formulations designed for high temperature resistance		
R1171-P	BMI-5000 Powder	921213-77-6 (Y)	Imide-extended bismaleimide oligomer that exhibits excellent toughness in the cured state with intermediate cross-link density.	Where $n = 1$ to 10	<ul> <li>Low cross-link density</li> <li>Non-tacky</li> <li>Film-forming</li> <li>Maleimide functional oligomer</li> <li>Cures to a tough thermoset</li> <li>Additive to enhance toughness in thermoset compositions</li> </ul>	Light Yellow Powder	Solid	<ul> <li>Film adhesives</li> <li>Thermally resistant adhesives</li> </ul>		
R1171-T	BMI-5000 Toluene	921213-77-6 (Y)	Imide-extended bismaleimide oligomer that exhibits excellent toughness in the cured state with intermediate cross-link density.	$\begin{cases} \left( \begin{array}{c} \left( \left( \begin{array}{c} \left( \begin{array}{c} \left( \left( \begin{array}{c} \left( \left( \begin{array}{c} \left( $	<ul> <li>Low cross-link density</li> <li>Non-tacky</li> <li>Film-forming</li> <li>Maleimide functional oligomer</li> <li>Cures to a tough thermoset</li> <li>Additive to enhance toughness in thermoset compositions</li> </ul>	Dark Brown Liquid	1,000	<ul> <li>Film adhesives</li> <li>Thermally resistant adhesives</li> </ul>		

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PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS	
IMIDE-EXTENDED BISMALEIMIDES continued									
R1191	BMI-1700	1224691-98-8 (Y)	An amorphous, low molecular weight bismaleimide oligomer that exhibits good adhesion to a variety of substrates	$\left\{ \left( \frac{1}{\sqrt{1 + \frac{1}{1 + \frac{1}{1 + \frac{1}{\sqrt{1 + \frac{1}{1 + \frac{1}{\sqrt{1 + \frac{1}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}}$	<ul> <li>Soluble in many reactive diluents</li> <li>Hydrophobic</li> <li>Superior thermal stability</li> <li>High adhesion to various substrates</li> </ul>	Amber High Viscous Liquid	30,000 ± 10,000 (60°C)	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> <li>Adhesion to metal</li> </ul>	
R1203	BMI-1500	1290041-56-3 (Y)	An amorphous, low molecular weight bismaleimide oligomer that exhibits good adhesion to a variety of substrates	$ \int_{n}^{n} \left( c_{aa} H_{2} - N \right) \int_{n}^{n} c_{aa} H_{2} - N \int_{n}^{n} \int_{n}^{n} c_{aa} H_{2} - N \int_{n}^{n} \int_{n}^{n} dt = 1 \text{ to } 10 $	<ul> <li>Soluble in many reactive diluents</li> <li>Hydrophobic</li> <li>Superior thermal stability</li> <li>High adhesion to various substrates</li> </ul>	Amber Viscous Liquid	20,000 ± 10,000 (60°C)	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> <li>Adhesion to metal</li> </ul>	
R1225	BMI-3000 CG	921213-77-6 (Y)	Low cost bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides.	Where n = 1 to 10	<ul> <li>Low cost</li> <li>Toughener</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>Superior thermal stability</li> </ul>	Light Yellow Powder	Solid	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> <li>Adhesion to metal</li> </ul>	
R1232	BMI-1400	1224691-98-8 (Y)	An amorphous, low molecular weight bismaleimide oligomer that exhibits good adhesion to a variety of substrates	$ \left\{ \left( \begin{array}{c} & & \\ & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ & & \\ \end{array} \right)^{-1} \left( \begin{array}{c} & & \\ \end{array} \right)^{-1} \left( \begin{array}{c$	<ul> <li>Specialty formulated lower viscosity version of BMI- 1700</li> </ul>	Amber High Viscous Liquid	6,500 ± 1,000 (60°C)	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> <li>Adhesion to metal</li> </ul>	
R1288	BMI-3000J Powder	921213-77-6 (Y)	Bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides	Where n = 1 to 10	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>Superior thermal stability</li> </ul>	Light Yellow Powder	Solid	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> <li>Adhesion to metal</li> </ul>	

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PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS		
IMIDE-	IMIDE-EXTENDED BISMALEIMIDES continued									
R1288S	BMI-3000 Solution	921213-77-6 (Y)	Bismaleimide oligomer that exhibits excellent flexibility and, on cure, forms very tough hydrophobic polyimides	Where $n = 1$ to 10	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>Excellent dielectric properties</li> <li>Superior thermal stability</li> </ul>	Light Amber Liquid	N/A	<ul> <li>Additive to increase flexibility, hydrophobicity and thixotropy.</li> </ul>		
R1316	BMI-2500	2020378-57-6 (Y)	Designed to extend the range of applications suitable for use with Designer Molecules, Inc. Imide-Extended Bismaleimide Oligmers to those in need of higher Tg and modulus.	N/A	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>Superior thermal stability</li> <li>Low pH hydrolytic resistance</li> <li>Reduce resin bleed out</li> </ul>	Light Yellow Glassy Powder	Solid	<ul> <li>Additive to increase flexibility, hydrophobicity, thixotrophy</li> <li>Base resin – produces films that are tough, flexible, &amp; have good peel strength</li> </ul>		
R1334	BMI-6000	2095324-53-9 (N)	Has excellent thermal stability and workability. It is soluble in a variety of solvents such as cyclopentanone, cyclohexanone, MEK, DMF, DMAC, and NMP in combination with aromatic solvents	N/A	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>Super thermal stability</li> <li>Good dielectric properties</li> <li>Excellent workability</li> <li>High Tg</li> <li>Low CTE</li> </ul>	Light yellow powder	Solid	<ul> <li>Adhesive layer when laminating materials</li> <li>Adhesion promoter</li> </ul>		
R1354	BMI-2560	2126832-79-7 (N)	Designed to extend the range of applications suitable for use with the Designer Molecules, Inc. imide extended bismaleimide oligomers to those in need of higher Tg and modulus	N/A	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>Superior thermal stability</li> </ul>	Light yellow glassy powder	Solid	<ul> <li>An additive to increase flexibility, hydrophobicity and thixotropy</li> </ul>		
R1356	BMI-6100	2127116-97-4 (N)	A high molecular weight, curable bismaleimide (BMI) oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	N/A	<ul> <li>Flexibility / High strength</li> <li>Curability / Hydrophobicity</li> <li>Superior electrical properties</li> </ul>	Amber liquid	370	<ul> <li>Recommended for use as a polyimide (PI) replacement resin in CCL applications</li> </ul>		

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IMIDE-EXTENDED BISMALEIMIDES continued									
R1442	BMI-689M	1911605-95-2 (Y)	A unique low viscosity liquid bismaleimide based on a non-hydrogenated dimer diamine backbone and serves as a low cost alternative to DMI's BMI-689	$f_{M_{0}} = \int_{M_{0}} \int_$	<ul> <li>Low viscosity liquid BMI</li> <li>Hydrophobic</li> <li>Superior thermal stability</li> </ul>	Dark amber liquid	5,000 ± 2,000	<ul> <li>An additive or base resin in adhesives that are designed for high temperature resistance</li> </ul>	
R1453	BMI-4200	N/A (N)	Designed to extend the range of applications suitable for use with DMI's imide extended BMI oligomers to those in need of a higher Tg and modulus. It can be processed in a resin system as a solid or dissolved in a solvent.	N/A	<ul> <li>Toughener</li> <li>Hydrophobic</li> <li>Increased Tg and modulus for demanding applications</li> <li>Superior thermal stability</li> </ul>	Yellow granules	Solid	<ul> <li>An additive to increase hydrophobicity and thixotropy</li> </ul>	

FUNC	FUNCTIONAL CYCLOSILOXANES										
R1362	CS-697	257284-60-9 (Y)	A polyglycidyl ether cyclosiloxane monomer		<ul> <li>Multifunctional</li> <li>UV curable</li> <li>Low chloride</li> <li>Low viscosity</li> <li>Colorless</li> </ul>	Colorless Liquid	200	• UV curable additive			
R1366	CS-783	921214-21-3 (Y)	Methacrylate epoxy functional hybrid cyclosiloxane monomer	and the second s	<ul> <li>Dual cure mechanism</li> <li>Multifunctional</li> <li>UV Curable</li> <li>Low chloride</li> <li>Low viscosity</li> </ul>	Yellow Liquid	250	<ul> <li>Hybrid cures</li> <li>UV cures</li> <li>B-stageable adhesives</li> </ul>			

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PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS	
PHENYL ESTER EPOXY CURATIVES									
R1146	EC-234	926305-16-0 (Y-LVE)	Phenyl ester epoxy curative hybrid	CH <sub>3</sub> CH <sub>2</sub>	<ul><li>Hybrid cure</li><li>Low viscosity</li></ul>	Light Yellow Liquid	40	<ul> <li>UV adhesives</li> <li>B-stageable adhesives</li> </ul>	
R1147	EC-326	936555-33-8 (Y-LVE)	Bisphenol A based acetate/proprionate epoxy curative		<ul> <li>Hydrolytically resistant</li> <li>Low melting point</li> <li>Thermal stability</li> <li>Hydrophobic</li> <li>Toughener</li> <li>Does not impede free radical cure</li> </ul>	White/Yellow Solid	2,000	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> </ul>	
R1148	EC-392	107466-61-9 (Y)	Phenyl ester epoxy curative hybrid of diallyl bisphenol A	$CH_3$ $CH_3$ $CH_3$ $CH_3$ $CH_3$ $H_3C$ $CH_2$ $H_3C$	<ul> <li>Dual cure mechanism</li> <li>High cross-link density</li> <li>Multifunctional</li> <li>Thermal stability</li> </ul>	Amber Liquid	2,500	<ul> <li>B-stageable adhesives</li> <li>Epoxy and BMI co- curative</li> </ul>	
R1149	EC-1074	926657-64-9 (Y)	A tetra-phenol epoxy curative derived from dimerdiol	HACTORY HE COM	<ul> <li>Low modulus</li> <li>Toughener</li> <li>Hydrolytically resistant thermosets</li> <li>Hydrophobic</li> <li>Thermal stability</li> </ul>	Amber Glassy Solid	Solid	<ul> <li>Film Adhesives</li> <li>Pre-applied adhesive compositions</li> </ul>	
R1165	EC-861	1071523-12-0 (Y)	Phenyl acetate epoxy curative	H <sub>6</sub> C- H <sub></sub>	<ul> <li>Low modulus</li> <li>Toughener</li> <li>Hydrolytically resistant thermosets</li> <li>Hydrophobic</li> <li>Thermal stability</li> <li>Does not impede free radical cure</li> </ul>	Amber/Yello w Liquid	2,500	Low stress epoxy thermosets	

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PHENYL ESTER EPOXY CURATIVES continued									
R1170	EC-298	1044794-71-7 (Y-LVE)	Difunctional phenyl ester epoxy curative	H <sub>3</sub> C O CH <sub>3</sub>	<ul> <li>Stable</li> <li>Low viscosity</li> <li>Does not impede free radical cure</li> </ul>	Light Yellow Liquid	500	<ul> <li>Thermoset adhesives</li> <li>Curative for epoxy /(meth)acrylate hybrids</li> <li>Hybrid epoxy/free radical thermosets</li> </ul>	
R1227	EC-312	10192-62-8 (Y)	Difunctional phenyl ester epoxy curative	$0 = \underbrace{\begin{pmatrix} CH_3 \\ CH_3 \end{pmatrix}}_{CH_3} \underbrace{\begin{pmatrix} H_3C \\ CH_3 \end{pmatrix}}_{CH_3} 0$	<ul> <li>Low cost</li> <li>Low melting point</li> <li>Thermal stability</li> <li>Hydrophobic</li> <li>Does not impede free radical cure</li> </ul>	Fine White Powder	Solid	<ul> <li>Film adhesives</li> <li>Pre-applied adhesives</li> </ul>	
LATENT EPOXY CATALYSTS									
R1198	ECAT Series ECAT-243	1253404-90-8 (Y			<ul> <li>Good solubility in most epoxy monomers</li> <li>Excellent latency characteristics</li> </ul>	Refer to		Electronic mold	

R1198 R1207 R1208 R1209	ECAT-243 ECAT-259 ECAT-353 ECAT-434		Imidazole Epoxy Catalysts	Unavailable	<ul> <li>Excellent latency characteristics</li> <li>Can be used as a catalyst or curative</li> <li>Turnable cures</li> <li>Promotes clean, rapid monomodal cures</li> </ul>	Refer to TDS	Solid	<ul><li>Electronic mold compounds</li><li>Underfills</li></ul>	
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MONOFUNCTIONAL MONOMERS									
R1121	MM-281	57079-01-3 (Y-LVE)	Maleimidoundecanoic Acid (MUDA)	ристория с со с	<ul> <li>Flexible aliphatic backbone</li> <li>Malemide and carboxylic acid functional groups</li> <li>Adhesion promoter</li> </ul>	White to Off- white Powder	N/A	<ul> <li>Intermediate for ester and amide linked maleimide monomers</li> </ul>	

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ΜΟΝΟΙ	MONOFUNCTIONAL MONOMERS continued									
R1134	MM-290	903876-45-9 (Y)	Isobornyl Cyclohexyl Acrylate	H <sub>3</sub> C H <sub>3</sub> C H <sub>3</sub> C H <sub>3</sub> C	<ul> <li>Lower weight loss on cure than Isobornyl Acrylate (IBOA)</li> <li>Mild, pleasant odor</li> <li>Hydrolytic resistance</li> </ul>	Light Tan Liquid	250	UV or peroxide cured resins, coatings, or adhesives		
R1139	MM-220	93962-84-6 (Y-LVE)	Tricyclodecane Acrylate	H <sub>2</sub> C	<ul> <li>Low weight loss on cure</li> <li>Helps reduce cure shrinkage</li> <li>Low viscosity</li> </ul>	Light Yellow Liquid	< 100	UV cure coatings		
R1173	MM-204	33791-58-1 (Y)	Monofunctional acrylate monomer		<ul> <li>Low viscosity</li> <li>High glass transition temperature</li> <li>Low cure shrinkage</li> <li>Hydrolytically resistant</li> <li>Diluent for thermoset resins</li> <li>High Tg</li> </ul>	Light Tan Liquid	50	<ul> <li>UV or peroxide cured resins, coatings, or adhesives</li> </ul>		
R1175	MM-211	55750-53-3 (N)	An intermediate chain length, maleimide terminated carboxylic acid	O OH	<ul> <li>Flexible aliphatic backbone</li> <li>Maleimide and carboxylic acid functional groups</li> <li>Adhesion promoter</li> </ul>	White/Light Yellow Powder	N/A	<ul> <li>Intermediate for ester and amide linked maleimide monomers</li> </ul>		
R1197	MM-304	N/A (N)	Isobornyl Cyclohexyl Methacrylate	$H_{3C}$ $O$ $H_{3C}$ $CH_{2}$ $H_{3C}$	<ul> <li>Very low color</li> <li>Lower weight loss on cure than Isobornyl Methacrylate (IBOMA)</li> <li>Mild, pleasant odor</li> <li>Hydrolytic resistance</li> </ul>	Colorless Liquid	80	<ul><li>Dental</li><li>Reactive diluent</li></ul>		
R1233	MM-348	132010-64-1 (N)	Maleimide Terminated 9- Octadecene	Hac	<ul> <li>Maleimide functional reactive diluents</li> </ul>	Light brown	Semi-solid	<ul> <li>Reactive diluent</li> </ul>		

Designer Molecules Inc.		PRODUCT SELECTOR GUIDE								
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POLYI	POLYESTER ACRYLATE METHACRYLATES (PEAM)									
R1096	PEAM-645	921213-39-0 (Y)	Polyester acrylate/methacrylate	$H_{C} = \int_{U_{L}} \int_{U_{$	<ul> <li>High Tg</li> <li>High modulus</li> <li>Low CTE</li> <li>High adhesion I</li> <li>Thermal stability</li> </ul>	Amber Liquid	6,500	Low CTE thermosets		
R1111	PEAM-1044	921214-61-1 (Y)	Polyester acrylate/methacrylate	$\frac{1}{\sqrt{2}} \left( \frac{1}{\sqrt{2}} \right)^{-1} \left( \frac{1}{\sqrt$	<ul> <li>Low warpage</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>Thermal stability</li> </ul>	Amber Liquid	(40°C)	<ul> <li>Low stress coatings</li> </ul>		
R1144	PEAM-1769	921214-61-1 (Y)	Polyester acrylate/methacrylate	$\frac{1}{\sqrt{2}}$ Where n = 1 to 5	<ul> <li>Ultra-low modulus</li> <li>Hydrophobic</li> <li>High adhesion *</li> <li>High thermal stability</li> <li>Adhesion to metals</li> <li>Flexibilizer</li> </ul>	Amber Liquid	4,500	Low stress     coatings		

POLYESTER METHACRYLATES (PEM)										
R9990	PEM-665	N/A (N)	Methacrylate terminated polyester oligomer	$\overset{H_1C_2 \subset H_3}{\sim} (f) = (f)$	<ul> <li>Low color</li> <li>Low cure shrinkage</li> <li>Thermal stability</li> <li>Tough</li> </ul>	Light Yellow Tint Liquid	6,500 (50°C)	Dental BisGMA     replacement		

Designer Molecules Inc.		PR	PRODUCT SELECTOR GUIDE					
PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS
FUNCT	IONAL URE	THANES						
R1095	U-793	869488-57-3 920758-62-9 902742-80-9 (Y)	Urethane resin functionalized with a methacrylate and an epoxy	Unavailable	<ul> <li>Low color</li> <li>Low cure shrinkage</li> <li>Thermal stability</li> <li>Tough</li> </ul>	Light Yellow Tint Liquid	6,500 (50°C)	Dental
R1102	U-835	869488-57-3 1003557-45-6 1003612-76-7 (Y-LVE)	Urethane resin functionalized with acrylate and methacrylate end groups	Unavailable	<ul> <li>Low modulus</li> <li>Excellent hydrolytic resistance</li> <li>High adhesion *</li> <li>Adhesion to metals</li> <li>Flexibilizer</li> </ul>	Light Yellow Liquid	20,000	<ul> <li>Dental</li> <li>Moisture resistant coatings</li> </ul>
R1216	U-347	1371570-15-8 (N)	Phenyl glycerol urethane dimethacrylate (PGDMA)	$H_3C$ $H_2C$ H	<ul> <li>Low cure shrinkage</li> <li>Colorless</li> <li>Good refractive index</li> <li>Not bisphenol A based</li> </ul>	Clear Colorless Liquid	9,500	<ul> <li>Dental</li> <li>Moisture resistant coatings</li> </ul>
R1228	U-471	72869-86-4 (Y)	TMDI urethane dimethacrylate monomer	$\begin{split} & \mu_{0} \mathcal{C} \overset{\beta}{\overset{\beta}{\overset{\beta}{\overset{\beta}{\overset{\beta}{\overset{\beta}{\overset{\beta}{\beta$	<ul><li>Low color</li><li>Low cure shrinkage</li></ul>	Slight Yellow Liquid	8,000	Dental
R1230	U-483	N/A (N)	IPDI urethane dimethacrylate	$H_2C \underbrace{ \begin{array}{c} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	<ul> <li>Low viscosity</li> <li>Low cure shrinkage</li> <li>Colorless</li> <li>Not bisphenol A based</li> </ul>	Clear Colorless Liquid	5,000	<ul> <li>Dental</li> <li>Moisture resistant coatings</li> <li>Light cure coatings</li> </ul>
R1238	U-847	86499-57-3 (N)	DDI urethane dimethacrylatemonomer		<ul> <li>Low modulus</li> <li>Low color</li> <li>Low cure shrinkage</li> <li>Hydrophobic</li> <li>Flexibilizer</li> </ul>	Light Yellow Liquid	2,500	<ul> <li>Dental</li> <li>Moisture resistant coatings</li> </ul>

	GIGNER OLECULES I	NC.	PR	PRODUCT SELECTOR GUIDE					
PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS	
FUNCTIONAL URETHANES continued									

R1266	U-443	67910-48-9 (N)	TMDI urethane diacrylate monomer	$\begin{array}{c} H_{12} \subset \ensuremath{\overset{\frown}{\longrightarrow}} \overset{$	Excellent Curing Properties	Clear, Colorless, Oil	5,500	Light-cured coating resins
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FORMULATED PRODUCTS									
R1353	DMI-2575	Mixture (Y)	Unique low viscosity liquid bismaleimide based formulation suitable for use as a base resin system for spray applications	Mixture	<ul> <li>Pre-catalyzed</li> <li>Extended pot-life (&lt; 6mo. @ room temp)</li> <li>Hydrophobis</li> <li>Solvent free</li> <li>Superior thermal stability</li> <li>Does not require refrigerated shipping</li> </ul>	Amber liquid	1400 ± 300	<ul> <li>Spray coating applications</li> </ul>	
R1397	DMI-3006A	Mixture (Y)	Modified polymide based negative type photoresist	Mixture	<ul> <li>Low modulus</li> <li>Very high electrical reliability</li> <li>UV cured-low thermal requirements</li> <li>Low cure shrinkage</li> <li>High heat resistance</li> <li>Good electrical properties</li> </ul>	Amber liquid	250	Wafer buffer coating	
R1398	DMI-2555	Mixture (Y)	A BMI-based coating for dispense applications	Mixture	<ul> <li>Pre-catalyzed</li> <li>Low modulus</li> <li>Hydrophobic</li> <li>Excellent hydrolytic resistance</li> <li>Low stress</li> <li>Adhesion to metals</li> <li>Flexibilizer</li> </ul>	Yellow to Dark Amber Liquid	900 ± 200	<ul> <li>Die top coating applications</li> </ul>	

DESIGNER MOLECULES INC.			PRODUCT SELECTOR GUIDE					
PART NUMBER	CATALOG NAME	CAS / TSCA Listed (Y/N)	DESCRIPTION	STRUCTURE**	FEATURES	APPEARANCE	VISCOSITY (cP @ 25°C)	SUGGESTED APPLICATIONS
IMIDE-	LINKED							
R1363	ILR-1363	Mixture (N)	A high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	Unavailable	<ul> <li>High strength</li> <li>Flexible</li> <li>Hydrophobic</li> <li>High heat resistance</li> <li>Good electrical properties</li> </ul>	Amber liquid	750	<ul> <li>A polyimide (PI) replacement resin</li> </ul>
R1399	ILR-1399	3027864-14-5 (N)	A proprietary high molecular weight functionalized polyimide designed specifically to resist degradation when exposed to elevated temperatures for extended durations	Unavailable	<ul> <li>Thermally curable</li> <li>Tough</li> <li>Superior thermal stability</li> <li>Hydrophobic</li> </ul>	Amber liquid	15,000 @ 25% Solids	• For use in LED assembly applications or where high temperature stability is required.
R1400	ILR-1400	2489312-38-9 (N)	High molecular weight non- functionalized polyimide with excellent physical properties	Unavailable	<ul> <li>Very Flexible film</li> <li>Good thermal stability (Td = &gt; 400°C)</li> <li>Good wetting property post b-stage on Copper foil</li> <li>Superior dielectric properties</li> <li>Low water absorption</li> <li>Soluble in most aromatic and aliphatic solvents</li> </ul>	Amber liquid	1,500 @ 15% Solids	<ul> <li>For use where flexibility and good electrical properties are required</li> </ul>
R1401	ILR-1401	Mixture (Y)	A high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	Unavailable	<ul> <li>Very low material shrinkage</li> <li>Flexible / high strength</li> <li>Curability &amp; Very low modulus</li> <li>Hydrophobic / low water absorption</li> </ul>	Amber liquid	5,000 @ 20% Solids	<ul> <li>For use in applications that require high temperature resin performance such as CCL</li> </ul>
R1402	ILR-1402	Mixture (Y)	A high molecular weight, curable oligomer mixture suitable for use as the base resin in a variety of microelectronic assembly applications	Unavailable	<ul> <li>Very low material shrinkage</li> <li>Flexible / high strength</li> <li>Curability &amp; Very low modulus</li> <li>Hydrophobic / low water absorption</li> </ul>	Amber liquid	4,000 @ 20% Solids	<ul> <li>For use in applications that require high temperature resin performance such as CCL</li> </ul>
R1457	ILR-1457	3027864-14-5 (N)	A proprietary high molecular weight functionalized polyimide designed specifically to resist degradation when exposed to elevated temperatures for extended durations	Unavailable	<ul> <li>Thermally curable</li> <li>Tough</li> <li>Superior thermal stability</li> <li>Hydrophobic</li> </ul>	Amber liquid	2,500 @ 25% Solids	<ul> <li>For use in high temperature adhesive applications</li> </ul>

## ALL DATA PROVIDED FOR REFERENCE ONLY AND MAY VARY BY TEST METHOD

- \* Various substrates \*\* Many of the structures are an idealized representation of a statistical distribution
- \*\*\* Supercooled \*\*\*\* Storage at < 25°C will result in precipitation of some solids. The fully liquid state can be regenerated by warming to 40°C until all solids dissolve
- LVE Material manufactured under Low Volume Exemption (LVE) in compliance with Section 5(h)(4) of the Toxic Substances Control Act (TSCA), 15 U.S.C.

TO PLACE AN ORDER, REQUEST SAMPLES, OR TO SPEAK WITH US ABOUT DEVELOPING A PRODUCT FOR YOUR CHEMICAL NEEDS, CONTACT US AT 858-348-1122.